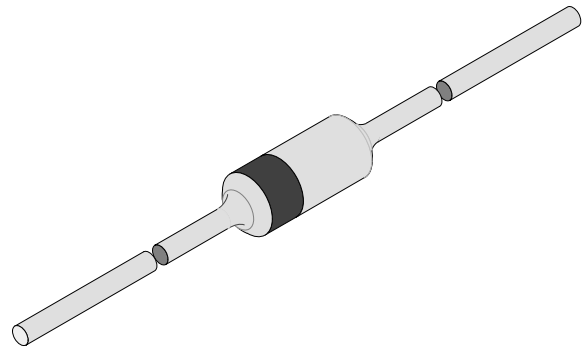


Silicon Epitaxial Planar Z-Diodes

Features

- Very sharp reverse characteristic
- Low reverse current level
- Very high stability
- Low noise
- Available with tighter tolerances



94 9367

Applications

Voltage stabilization

Absolute Maximum Ratings

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Value	Unit
Power dissipation	$l=4\text{mm}$, $T_L=25^\circ\text{C}$		P_V	500	mW
Z-current			I_Z	P_V/V_Z	mA
Junction temperature			T_j	175	$^\circ\text{C}$
Storage temperature range			T_{stg}	$-65\dots+175$	$^\circ\text{C}$

Maximum Thermal Resistance

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	$l=4\text{mm}$, $T_L=\text{constant}$	R_{thJA}	300	K/W

Characteristics

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F=200\text{mA}$		V_F			1.5	V

Type	V _{Zmin.} (V)	V _{Zmax.} (V)	Type	V _{Zmin.} (V)	V _{Zmax.} (V)	r _{Zmax.} (Ω)	at I _Z (mA)	I _{Rmax.} (μA)	at V _R (V)
TZX2V4	2.3	2.6	TZX2V4 - A	2.3	2.5	100	5	5	0.5
			TZX2V4 - B	2.4	2.6				
TZX2V7	2.5	2.9	TZX2V7 - A	2.5	2.7	100	5	5	0.5
			TZX2V7 - B	2.6	2.8				
			TZX2V7 - C	2.7	2.9				
TZX3V0	2.8	3.2	TZX3V0 - A	2.8	3.0	100	5	5	0.5
			TZX3V0 - B	2.9	3.1				
			TZX3V0 - C	3.0	3.2				
TZX3V3	3.1	3.5	TZX3V3 - A	3.1	3.3	100	5	5	1
			TZX3V3 - B	3.2	3.4				
			TZX3V3 - C	3.3	3.5				
TZX3V6	3.4	3.8	TZX3V6 - A	3.4	3.6	100	5	5	1
			TZX3V6 - B	3.5	3.7				
			TZX3V6 - C	3.6	3.8				
TZX3V9	3.7	4.1	TZX3V9 - A	3.7	3.9	100	5	5	1
			TZX3V9 - B	3.8	4.0				
			TZX3V9 - C	3.9	4.1				
TZX4V3	4.0	4.5	TZX4V3 - A	4.0	4.2	100	5	5	1.5
			TZX4V3 - B	4.1	4.3				
			TZX4V3 - C	4.2	4.4				
			TZX4V3 - D	4.3	4.5				
TZX4V7	4.4	4.9	TZX4V7 - A	4.4	4.6	100	5	5	2
			TZX4V7 - B	4.5	4.7				
			TZX4V7 - C	4.6	4.8				
			TZX4V7 - D	4.7	4.9				
TZX5V1	4.8	5.3	TZX5V1 - A	4.8	5.0	100	5	5	2
			TZX5V1 - B	4.9	5.1				
			TZX5V1 - C	5.0	5.2				
			TZX5V1 - D	5.1	5.3				
TZX5V6	5.2	5.9	TZX5V6 - A	5.2	5.5	40	5	5	2
			TZX5V6 - B	5.3	5.6				
			TZX5V6 - C	5.4	5.7				
			TZX5V6 - D	5.5	5.8				
			TZX5V6 - E	5.6	5.9				
TZX6V2	5.7	6.6	TZX6V2 - A	5.7	6.0	15	5	1	3
			TZX6V2 - B	5.9	6.1				
			TZX6V2 - C	6.0	6.3				
			TZX6V2 - D	6.1	6.4				
			TZX6V2 - E	6.3	6.6				

Type	V _{Zmin.} (V)	V _{Zmax.} (V)	Type	V _{Zmin.} (V)	V _{Zmax.} (V)	r _{Zmax.} (Ω)	at I _Z (mA)	I _{Rmax.} (μA)	at V _R (V)
TZX6V8	6.4	7.2	TZX6V8 - A	6.4	6.7	15	5	1	3.5
			TZX6V8 - B	6.6	6.9				
			TZX6V8 - C	6.7	7.0				
			TZX6V8 - D	6.9	7.2				
TZX7V5	7.0	7.9	TZX7V5 - A	7.0	7.3	15	5	1	5.0
			TZX7V5 - B	7.2	7.6				
			TZX7V5 - C	7.3	7.7				
			TZX7V5 - D	7.5	7.9				
TZX8V2	7.7	8.7	TZX8V2 - A	7.7	8.1	20	5	1	6.2
			TZX8V2 - B	7.9	8.3				
			TZX8V2 - C	8.1	8.5				
			TZX8V2 - D	8.3	8.7				
TZX9V1	8.5	9.7	TZX9V1 - A	8.5	8.9	20	5	1	6.8
			TZX9V1 - B	8.7	9.1				
			TZX9V1 - C	8.9	9.3				
			TZX9V1 - D	9.1	9.5				
			TZX9V1 - E	9.3	9.7				
TZX10	9.5	10.6	TZX10 - A	9.5	9.9	25	5	1	7.5
			TZX10 - B	9.7	10.1				
			TZX10 - C	9.9	10.3				
			TZX10 - D	10.2	10.6				
TZX11	10.4	11.6	TZX11 - A	10.4	10.8	25	5	1	8.2
			TZX11 - B	10.7	11.1				
			TZX11 - C	10.9	11.3				
			TZX11 - D	11.1	11.6				
TZX12	11.4	12.7	TZX12 - A	11.4	11.9	35	5	1	9.5
			TZX12 - B	11.6	12.1				
			TZX12 - C	11.9	12.4				
			TZX12 - D	12.2	12.7				
TZX13	12.4	13.4	TZX13 - A	12.4	12.9	35	5	1	10
			TZX13 - B	12.6	13.1				
			TZX13 - C	12.9	13.4				
TZX14	13.2	14.3	TZX14 - A	13.2	13.7	35	5	1	11
			TZX14 - B	13.5	14.0				
			TZX14 - C	13.8	14.3				
TZX15	14.1	15.5	TZX15 - A	14.1	14.7	40	5	1	11.5
			TZX15 - B	14.5	15.1				
			TZX15 - C	14.9	15.5				
TZX16	15.3	17.1	TZX16 - A	15.3	15.9	45	5	1	12
			TZX16 - B	15.7	16.5				
			TZX16 - C	16.3	17.1				

Type	V _{Zmin.} (V)	V _{Zmax.} (V)	Type	V _{Zmin.} (V)	V _{Zmax.} (V)	r _{Zmax.} (Ω)	at I _Z (mA)	I _{Rmax.} (μA)	at V _R (V)
TZX18	16.9	19.0	TZX18 - A	16.9	17.7	55	5	1	13
			TZX18 - B	17.5	18.3				
			TZX18 - C	18.1	19.0				
TZX20	18.8	21.2	TZX20 - A	18.8	19.7	60	2	1	15
			TZX20 - B	19.5	20.4				
			TZX20 - C	20.2	21.2				
TZX22	20.9	23.3	TZX22 - A	20.9	21.9	65	2	1	17
			TZX22 - B	21.6	22.6				
			TZX22 - C	22.3	23.3				
TZX24	22.9	25.5	TZX24 - A	22.9	24.0	70	2	1	19
			TZX24 - B	23.6	24.7				
			TZX24 - C	24.3	25.5				
TZX27	25.2	28.6	TZX27 - A	25.2	26.6	80	2	1	21
			TZX27 - B	26.2	27.6				
			TZX27 - C	27.2	28.6				
TZX30	28.2	31.6	TZX30 - A	28.2	29.6	100	2	1	23
			TZX30 - B	29.2	30.6				
			TZX30 - C	30.2	31.6				
TZX33	31.2	34.5	TZX33 - A	31.2	32.6	120	2	1	25
			TZX33 - B	32.2	33.6				
			TZX33 - C	33.2	34.5				
TZX36	34.2	38.0	TZX36 - A	34.2	35.7	140	2	1	27
			TZX36 - B	35.3	36.8				
			TZX36 - C	26.4	38.0				

Typical Characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified)

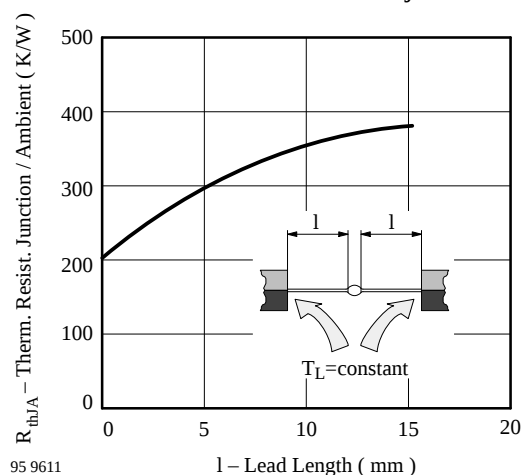


Figure 1. Thermal Resistance vs. Lead Length

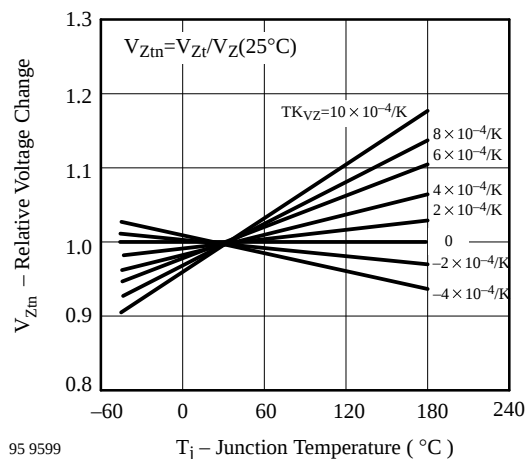


Figure 4. Typical Change of Working Voltage vs. Junction Temperature

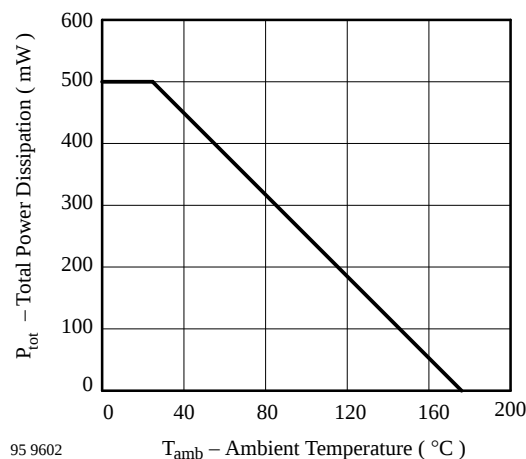


Figure 2. Total Power Dissipation vs. Ambient Temperature

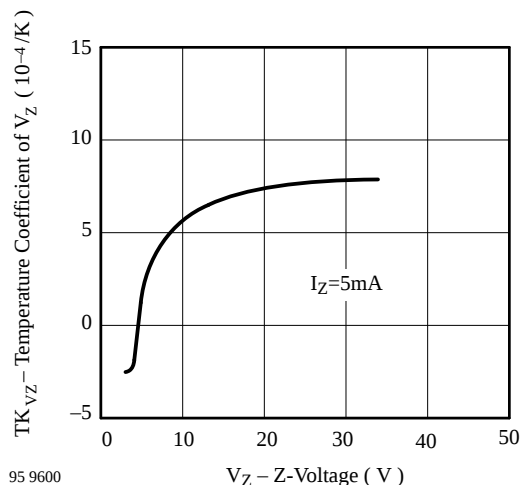


Figure 5. Temperature Coefficient of V_Z vs. Z-Voltage

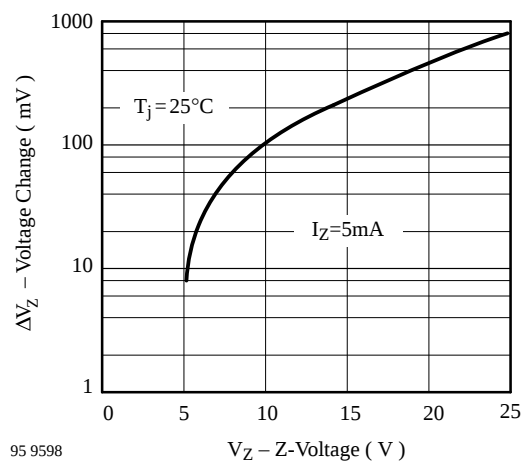


Figure 3. Typical Change of Working Voltage under Operating Conditions at $T_{amb} = 25^\circ\text{C}$

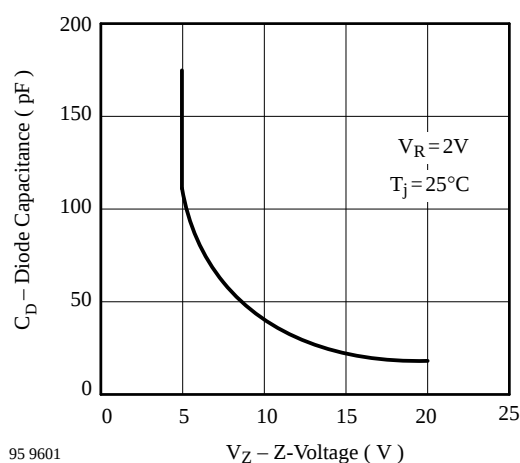


Figure 6. Diode Capacitance vs. Z-Voltage

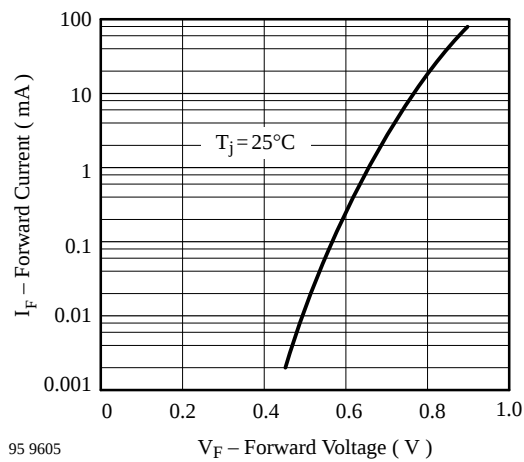


Figure 7. Forward Current vs. Forward Voltage

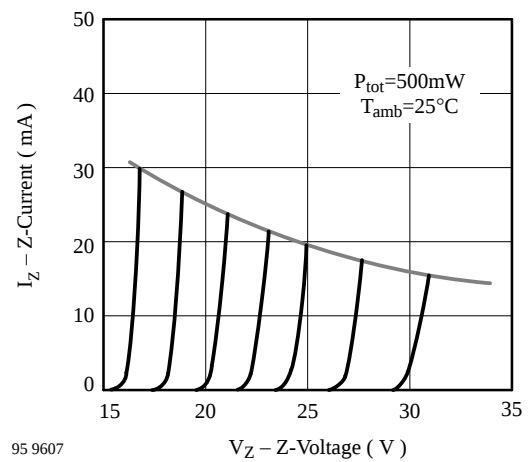


Figure 9. Z-Current vs. Z-Voltage

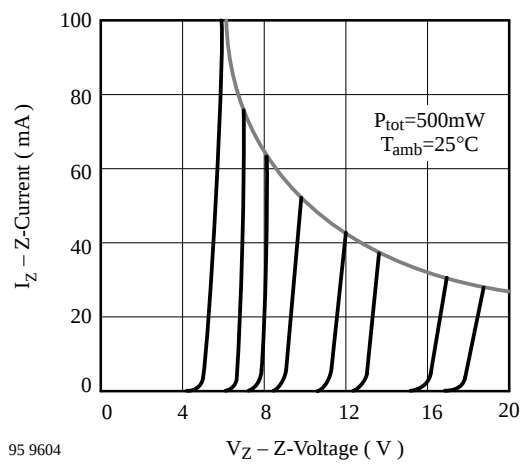


Figure 8. Z-Current vs. Z-Voltage

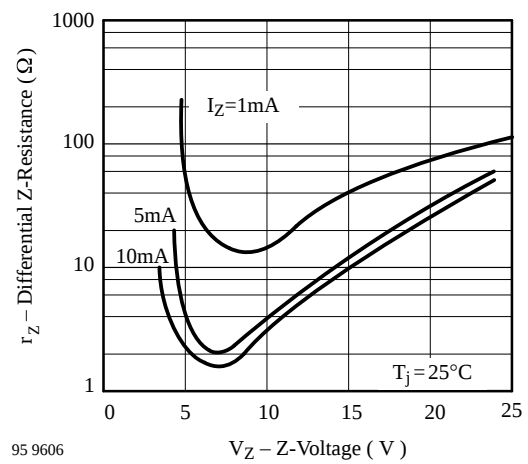


Figure 10. Differential Z-Resistance vs. Z-Voltage

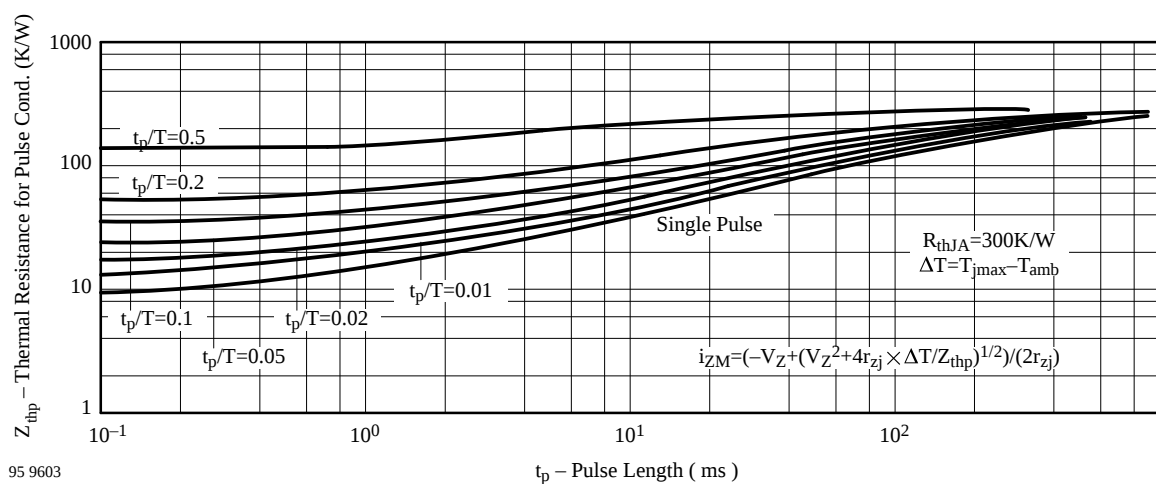


Figure 11. Thermal Response

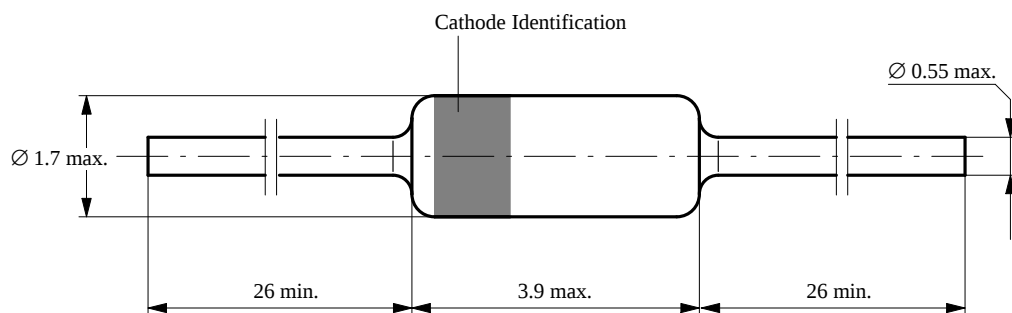
Dimensions in mm



technical drawings
according to DIN
specifications

94 9366

Standard Glass Case
54 A 2 DIN 41880
JEDEC DO 35
Weight max. 0.3g



Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

TEMIC TELEFUNKEN microelectronic GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany
Telephone: 49 (0) 7131 67 2831, Fax number: 49 (0) 7131 67 2423